## BST-505 Bga de Solda Tamanho Da Bola Para Micro Ferramentas De Reparo Do Telefone Móvel De Solda De Solda Diâmetro Da Esfera 0.2mm-0.65mm

#### PRODUCT DISPLAY



#### PRODUCT DETAILS





# A bottle of 25,000

### PRODUCT PHOTOGRAPH



Brand:	BST	Name:	solder ball	
Ingredients:	alloy:Sn63/Pb37	Size:	16*35mm	
Specifications:	0.2mm (55.4g/10bottle), 0.25mm (68.5G/10bottle), 0.3mm (65.8G/10bottle), 0.35mm (74G/10bottle), 0.4mm (86.3G/10bottle), 0.45mm (100.8 G/10bottle), 0.5mm (119.7G/bottle10), 0.55mm (142.7G/10bottle), 0.6mm (167.7G/10bottle)			
Quantity:	25,000 / bottle			
Features:	Tin ball is mainly connected to semiconductor wafers and circuit			
		pards and PCB boards, and small ball type tin electronic parts at transmit electronic signals.		



